## **Power MOSFET** 60 V, 1.2 mΩ, 276 A, Single N–Channel

#### Features

- Small Footprint (5x6 mm) for Compact Design
- Low R<sub>DS(on)</sub> to Minimize Conduction Losses
- Low Q<sub>G</sub> and Capacitance to Minimize Driver Losses
- These Devices are Pb-Free and are RoHS Compliant

#### **MAXIMUM RATINGS** (T<sub>J</sub> = $25^{\circ}$ C unless otherwise noted)

Parameter			Symbol	Value	Unit	
Drain-to-Source Voltage			V <sub>DSS</sub>	60	V	
Gate-to-Source Voltage			V <sub>GS</sub>	±20	V	
Continuous Drain	Steady	$T_C = 25^{\circ}C$	۱ <sub>D</sub>	276	А	
Current R <sub>0JC</sub> (Notes 1, 3)		T <sub>C</sub> = 100°C		175		
Power Dissipation	State	T <sub>C</sub> = 25°C	PD	167	W	
$R_{\theta JC}$ (Note 1)		$T_C = 100^{\circ}C$		67		
Continuous Drain	Steady State	$T_A = 25^{\circ}C$	۱ <sub>D</sub>	38	А	
Current R <sub>0JA</sub> (Notes 1, 2, 3)		T <sub>A</sub> = 100°C		24		
Power Dissipation		T <sub>A</sub> = 25°C	PD	3.2	W	
R <sub>θJA</sub> (Notes 1 & 2)		$T_A = 100^{\circ}C$		1.3		
Pulsed Drain Current	$T_{A} = 25$	°C, t <sub>p</sub> = 10 μs	I <sub>DM</sub>	900	А	
Operating Junction and Storage Temperature			T <sub>J</sub> , T <sub>stg</sub>	–55 to +175	°C	
Source Current (Body Diode)			۱ <sub>S</sub>	195	А	
Single Pulse Drain–to–Source Avalanche Energy $(I_{L(pk)} = 22 \text{ A})$			E <sub>AS</sub>	776	mJ	
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			ΤL	260	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State	$R_{\theta JC}$	0.75	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	39	

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

Surface-mounted on FR4 board using a 650 mm<sup>2</sup>, 2 oz. Cu pad.
Maximum current for pulses as long as 1 second is higher but is dependent

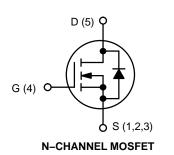
Maximum current for pulses as long as 1 second is higher but is dependen on pulse duration and duty cycle.

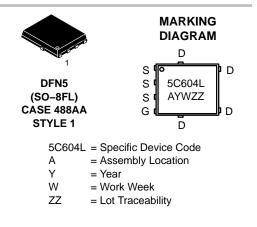


## **ON Semiconductor®**

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V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
60 V	1.2 mΩ @ 10 V	070 4
60 V	1.7 mΩ @ 4.5 V	276 A





#### ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

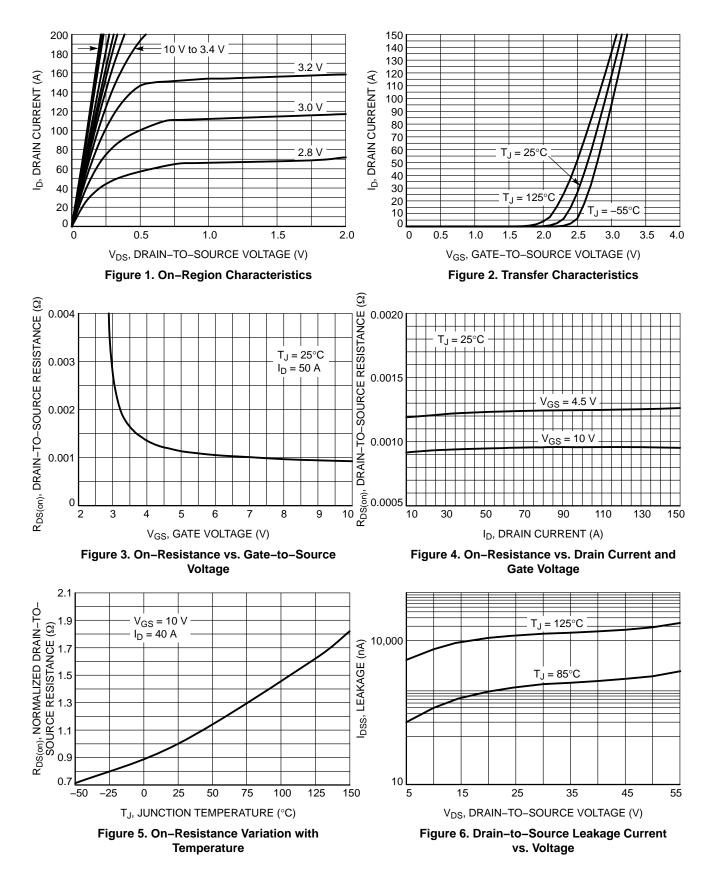
#### **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = $25^{\circ}$ C unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit	
OFF CHARACTERISTICS								
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS}$ = 0 V, I <sub>D</sub> = 250 $\mu$ A		60			V	
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /				22.9		mV/°C	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = 0 V,$	$T_J = 25^{\circ}C$			1.0		
		$V_{DS} = 60 V$	T <sub>J</sub> = 125°C			250	μΑ	
Gate-to-Source Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = 20 V				100	nA	
ON CHARACTERISTICS (Note 4)								
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}$ , $I_D = 250 \ \mu A$		1.2		2.0	V	
Threshold Temperature Coefficient	V <sub>GS(TH)</sub> /T <sub>J</sub>				-5.9		mV/°C	
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 50 A		0.93	1.2	mΩ	
		$V_{GS} = 4.5 V$	I <sub>D</sub> = 50 A		1.25	1.7		
Forward Transconductance	9 <sub>FS</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 50 A			180		S	
CHARGES, CAPACITANCES & GATE RE	SISTANCE							
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> = 0 V, f = 1 MHz, V <sub>DS</sub> = 25 V			8900			
Output Capacitance	C <sub>OSS</sub>				3750		pF	
Reverse Transfer Capacitance	C <sub>RSS</sub>				40			
Total Gate Charge	Q <sub>G(TOT)</sub>	$V_{GS}$ = 4.5 V, $V_{DS}$ = 30 V; $I_{D}$ = 50 A			52			
Total Gate Charge	Q <sub>G(TOT)</sub>	$V_{GS}$ = 10 V, $V_{DS}$ = 30 V; $I_{D}$ = 50 A			120		1	
Threshold Gate Charge	Q <sub>G(TH)</sub>	V <sub>GS</sub> = 4.5 V, V <sub>DS</sub> = 30 V; I <sub>D</sub> = 50 A			6.4		nC V	
Gate-to-Source Charge	Q <sub>GS</sub>				21.4			
Gate-to-Drain Charge	Q <sub>GD</sub>				12.7			
Plateau Voltage	V <sub>GP</sub>				2.8			
SWITCHING CHARACTERISTICS (Note 5	5)					-		
Turn–On Delay Time	t <sub>d(ON)</sub>				21.8			
Rise Time	tr	$V_{GS}$ = 4.5 V, $V_{DS}$ = 30 V, I <sub>D</sub> = 50 A, R <sub>G</sub> = 2.5 Ω			79.1		ns	
Turn-Off Delay Time	t <sub>d(OFF)</sub>				57.8			
Fall Time	t <sub>f</sub>				81.3			
DRAIN-SOURCE DIODE CHARACTERIS	STICS							
Forward Diode Voltage	V <sub>SD</sub>	$V_{GS} = 0 V,$ $I_{S} = 50 A$	$T_J = 25^{\circ}C$		0.78	1.2		
			T <sub>J</sub> = 125°C		0.64		V	
Reverse Recovery Time	t <sub>RR</sub>	V <sub>GS</sub> = 0 V, dIS/dt = 100 A/µs, I <sub>S</sub> = 50 A			98		1	
Charge Time	ta				45		ns	
Discharge Time	t <sub>b</sub>				53			
Reverse Recovery Charge	Q <sub>RR</sub>				190		nC	

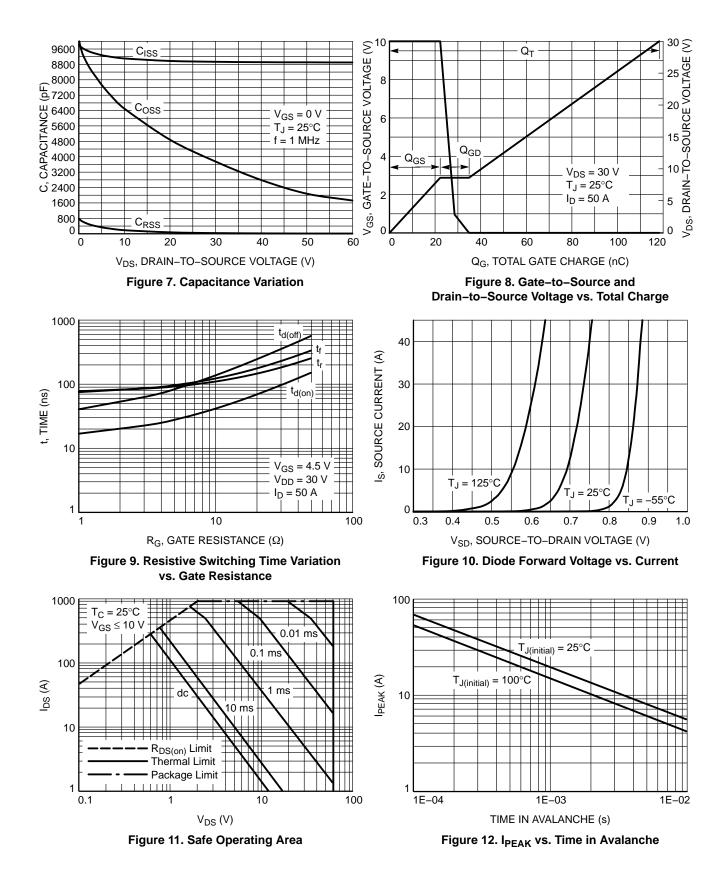
Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.
Switching characteristics are independent of operating junction temperatures.

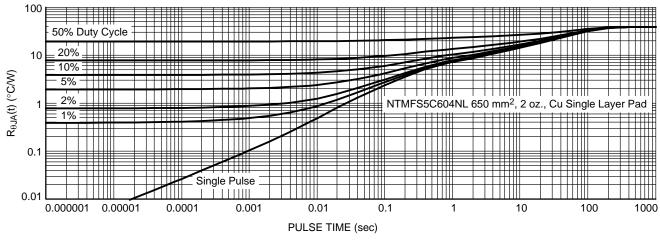
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

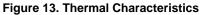
#### **TYPICAL CHARACTERISTICS**



#### **TYPICAL CHARACTERISTICS**





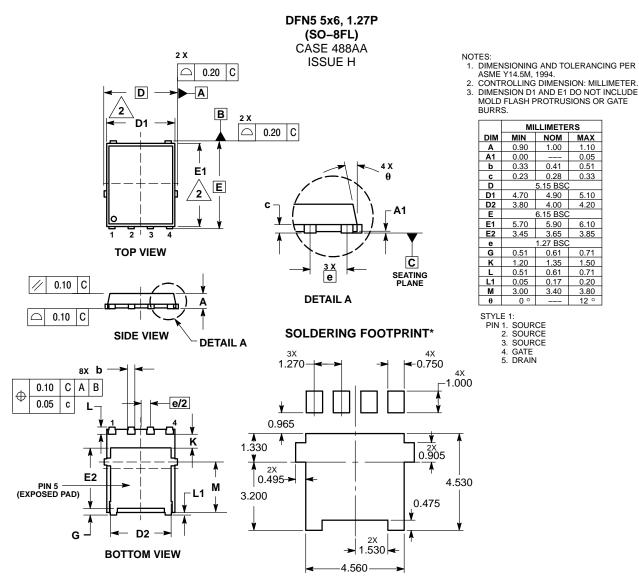


#### **DEVICE ORDERING INFORMATION**

Device	Marking	Package	Shipping <sup>†</sup>
NTMFS5C604NLT1G	5C604L	DFN5 (Pb–Free)	1500 / Tape & Reel
NTMFS5C604NLT3G	5C604L	DFN5 (Pb–Free)	5000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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